



CSD15380F3 20-V N-Channel FemtoFET™ MOSFET

1 Features

- Ultra-Low C_{ISS} and C_{OSS}
- Ultra-Low Q_g and Q_{gd}
- Ultra-Small Footprint
 - 0.73 mm × 0.64 mm
- Ultra-Low Profile
 - 0.35-mm Max Height
- Integrated ESD Protection Diode
 - Rated > 4-kV HBM
 - Rated > 2-kV CDM
- Lead and Halogen Free
- RoHS Compliant

2 Applications

- Optimized for Load Switch Applications
- Optimized for General Purpose Switching Applications
- Battery Applications
- Handheld and Mobile Applications

3 Description

This 20-V, 990-m Ω , N-Channel FemtoFET™ MOSFET is designed and optimized to minimize the footprint in many handheld and mobile applications. Ultra-low capacitance improves switching speeds. When used in data line applications, the low capacitance minimizes noise coupling. This technology is capable of replacing standard small signal MOSFETs while providing a substantial reduction in footprint size.

Product Summary

| $T_A = 25^\circ\text{C}$ | | TYPICAL VALUE | UNIT |
|--------------------------|-------------------------------|-------------------------|-----------------|
| V_{DS} | Drain-to-Source Voltage | 20 | V |
| Q_g | Gate Charge Total (4.5 V) | 0.216 | nC |
| Q_{gd} | Gate Charge Gate-to-Drain | 0.027 | nC |
| $R_{DS(on)}$ | Drain-to-Source On-Resistance | $V_{GS} = 2.5\text{ V}$ | 2220 m Ω |
| | | $V_{GS} = 4.5\text{ V}$ | 1170 m Ω |
| | | $V_{GS} = 8\text{ V}$ | 990 m Ω |
| $V_{GS(th)}$ | Threshold Voltage | 1.1 | V |

Ordering Information⁽¹⁾

| Device | Qty | Media | Package | Ship |
|-------------|------|-------------|---|---------------|
| CSD15380F3 | 3000 | 7-Inch Reel | Femto 0.73-mm × 0.64-mm Land Grid Array (LGA) | Tape and Reel |
| CSD15380F3T | 250 | 7-Inch Reel | | |

(1) For all available packages, see the orderable addendum at the end of the data sheet.

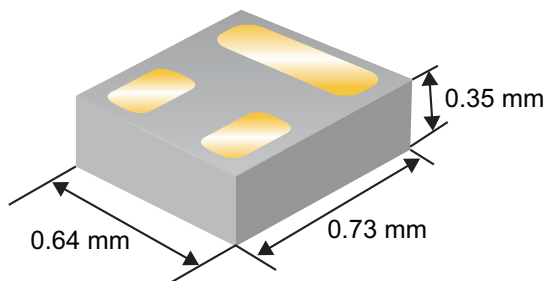
Absolute Maximum Ratings

| $T_A = 25^\circ\text{C}$ (unless otherwise stated) | | VALUE | UNIT |
|--|--|------------|------------------|
| V_{DS} | Drain-to-Source Voltage | 20 | V |
| V_{GS} | Gate-to-Source Voltage | 10 | V |
| I_D | Continuous Drain Current ⁽¹⁾ | 0.5 | A |
| I_{DM} | Pulsed Drain Current ⁽²⁾ | 1.6 | A |
| P_D | Power Dissipation ⁽¹⁾ | 500 | mW |
| $V_{(ESD)}$ | Human Body Model (HBM) | 4 | kV |
| | Charged Device Model (CDM) | 2 | kV |
| T_J , T_{stg} | Operating Junction and Storage Temperature | –55 to 150 | $^\circ\text{C}$ |

(1) Typical $R_{\theta JA} = 255^\circ\text{C/W}$ on 1-in² (6.45-cm²), 2-oz (0.071-mm) thick Cu pad on a 0.06-in (1.52-mm) thick FR4 PCB.

(2) Pulse duration $\leq 100\text{ }\mu\text{s}$, duty cycle $\leq 1\%$.

Typical Part Dimensions



Top View

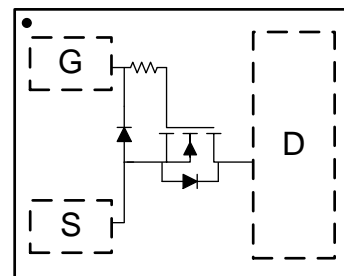


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4 Revision History

| DATE | REVISION | NOTES |
|----------|----------|------------------|
| May 2016 | * | Initial release. |

5 Specifications

5.1 Electrical Characteristics

 $T_A = 25^\circ\text{C}$ (unless otherwise stated)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|-------------------------|----------------------------------|---|-------|------|-------|------|
| STATIC CHARACTERISTICS | | | | | | |
| BV _{DSS} | Drain-to-source voltage | V _{GS} = 0 V, I _{DS} = 250 μA | 20 | | | V |
| I _{DSS} | Drain-to-Source leakage current | V _{GS} = 0 V, V _{DS} = 16 V | 50 | | | nA |
| I _{GSS} | Gate-to-source leakage current | V _{DS} = 0 V, V _{GS} = 10 V | 25 | | | nA |
| V _{GS(th)} | Gate-to-source threshold voltage | V _{DS} = V _{GS} , I _{DS} = 2.5 μA | 0.85 | 1.10 | 1.35 | V |
| R _{DS(on)} | Drain-to-source on-resistance | V _{GS} = 2.5 V, I _{DS} = 0.1 A | 2220 | | 4000 | mΩ |
| | | V _{GS} = 4.5 V, I _{DS} = 0.1 A | 1170 | | 1460 | mΩ |
| | | V _{GS} = 8 V, I _{DS} = 0.1 A | 990 | | 1190 | mΩ |
| g _{fs} | Transconductance | V _{DS} = 2 V, I _{DS} = 0.1 A | 0.64 | | | S |
| DYNAMIC CHARACTERISTICS | | | | | | |
| C _{iss} | Input capacitance | V _{GS} = 0 V, V _{DS} = 10 V, f = 1 MHz | 8.1 | | 10.5 | pF |
| C _{oss} | Output capacitance | | 5.9 | | 7.7 | pF |
| C _{rss} | Reverse transfer capacitance | | 0.13 | | 0.17 | pF |
| R _G | Series gate resistance | | 9.6 | | | Ω |
| Q _g | Gate charge total (4.5 V) | V _{DS} = 10 V, I _{DS} = 0.1 A | 0.216 | | 0.281 | nC |
| Q _{gd} | Gate charge gate-to-drain | | 0.027 | | | nC |
| Q _{gs} | Gate charge gate-to-source | | 0.077 | | | nC |
| Q _{g(th)} | Gate charge at V _{th} | | 0.048 | | | nC |
| t _{d(on)} | Turn on delay time | V _{DS} = 10 V, V _{GS} = 4.5 V, I _{DS} = 0.1 A, R _G = 0 Ω | 3 | | | ns |
| t _r | Rise time | | 1 | | | ns |
| t _{d(off)} | Turn off delay time | | 7 | | | ns |
| t _f | Fall time | | 7 | | | ns |
| DIODE CHARACTERISTICS | | | | | | |
| V _{SD} | Diode forward voltage | I _{SD} = 0.1 A, V _{GS} = 0 V | 0.85 | | 1 | V |

5.2 Thermal Information

 $T_A = 25^\circ\text{C}$ (unless otherwise stated)

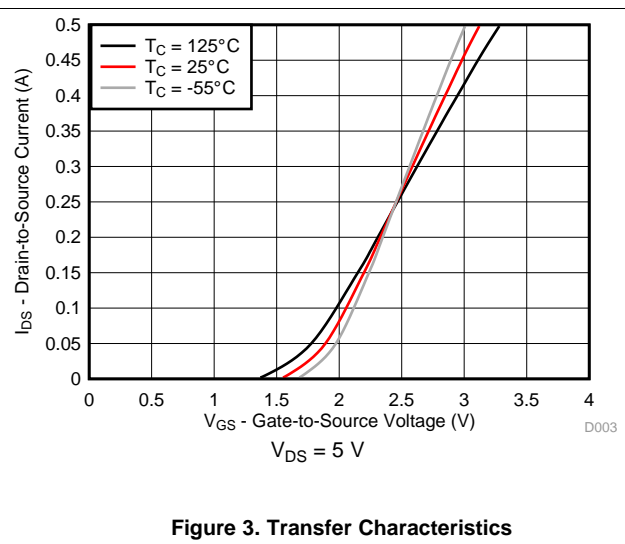
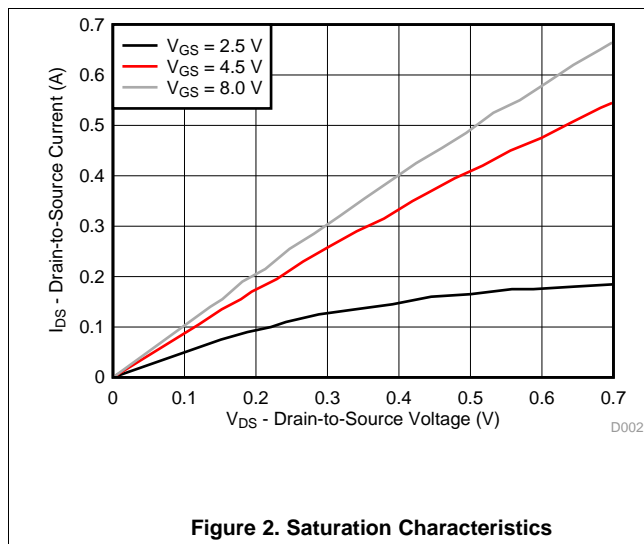
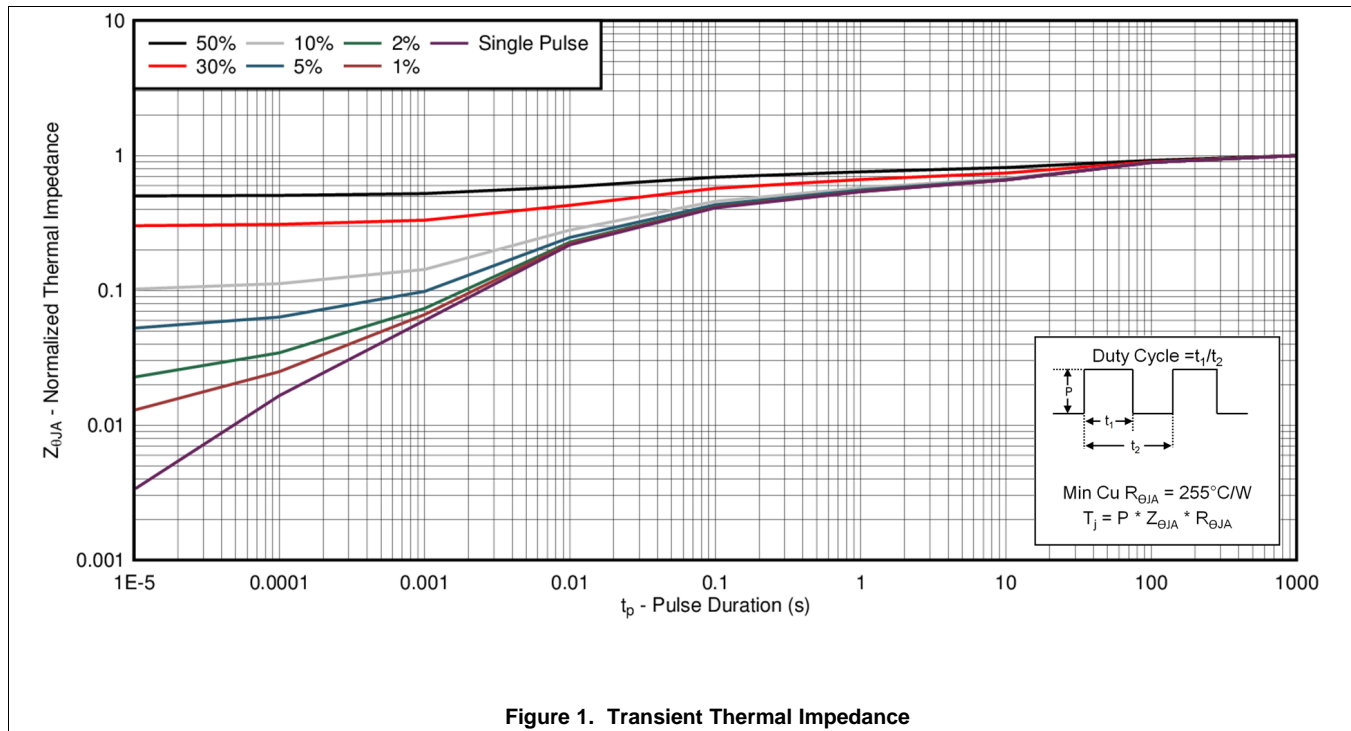
| THERMAL METRIC | | TYPICAL VALUES | UNIT |
|-----------------|---|----------------|--------------------|
| $R_{\theta JA}$ | Junction-to-ambient thermal resistance ⁽¹⁾ | 90 | $^\circ\text{C/W}$ |
| | Junction-to-ambient thermal resistance ⁽²⁾ | 255 | $^\circ\text{C/W}$ |

(1) Device mounted on FR4 material with 1-in² (6.45-cm²), 2-oz (0.071-mm) thick Cu.

(2) Device mounted on FR4 material with minimum Cu mounting area.

5.3 Typical MOSFET Characteristics

$T_A = 25^\circ\text{C}$ (unless otherwise stated)



Typical MOSFET Characteristics (continued)

$T_A = 25^\circ\text{C}$ (unless otherwise stated)

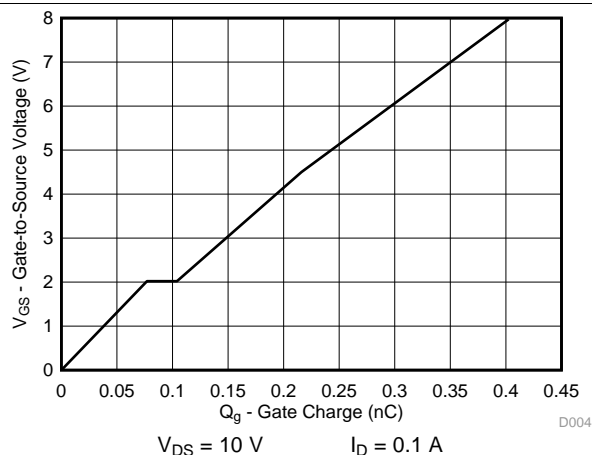


Figure 4. Gate Charge

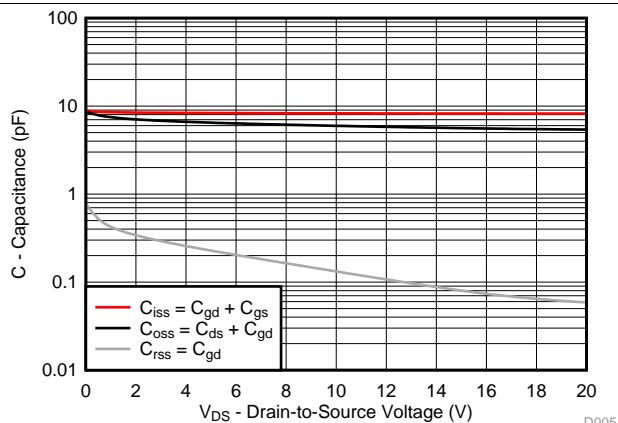


Figure 5. Capacitance

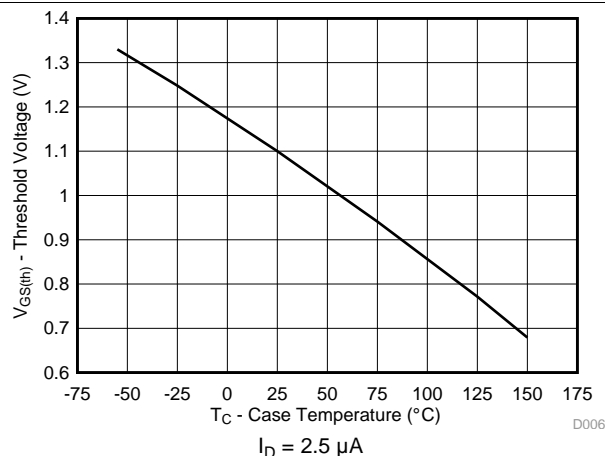


Figure 6. Threshold Voltage vs Temperature

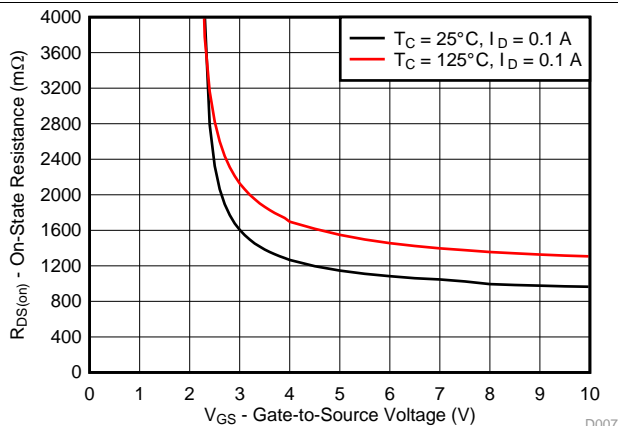


Figure 7. On-State Resistance vs Gate-to-Source Voltage

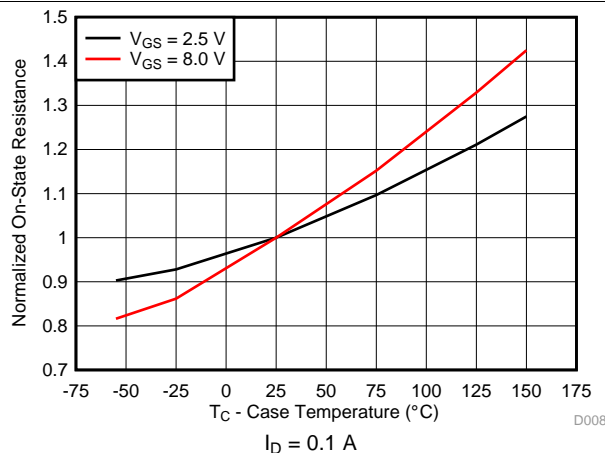


Figure 8. Normalized On-State Resistance vs Temperature

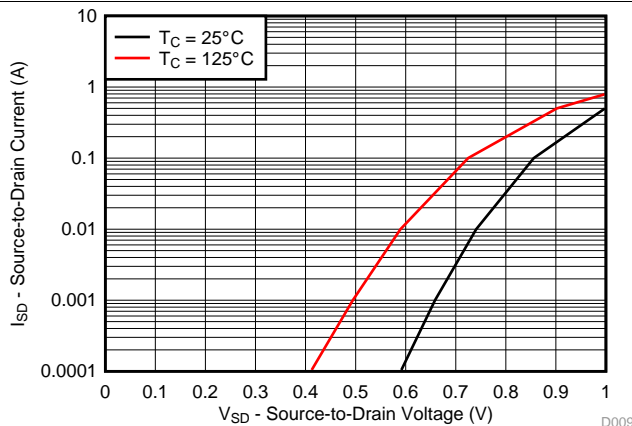
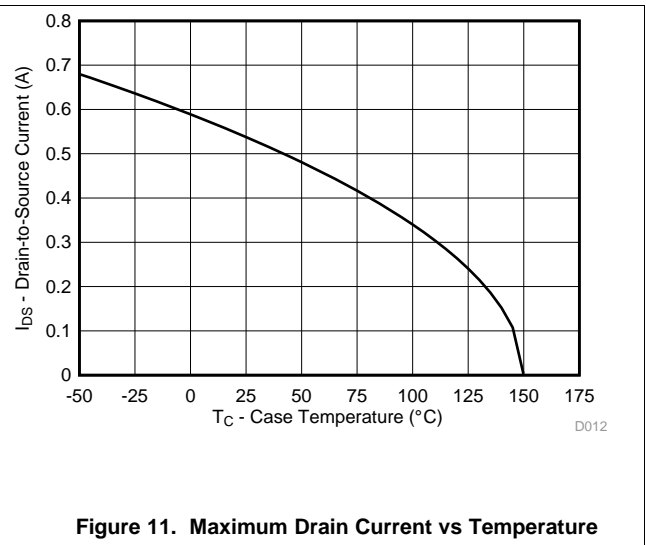
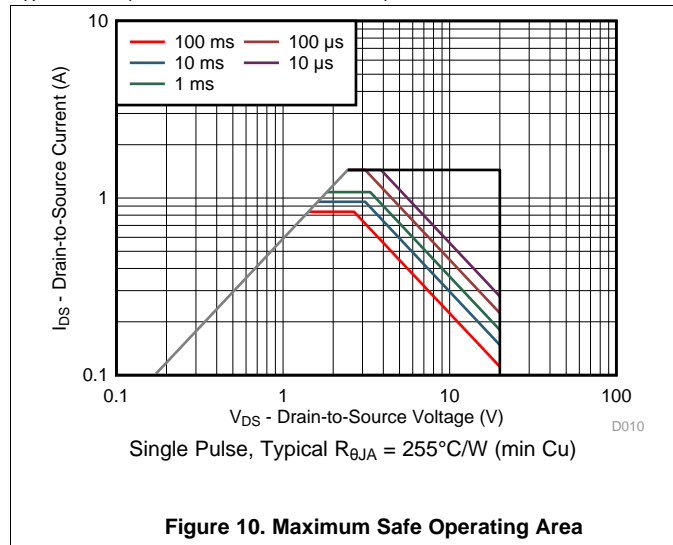


Figure 9. Typical Diode Forward Voltage

Typical MOSFET Characteristics (continued)

$T_A = 25^\circ\text{C}$ (unless otherwise stated)



6 Device and Documentation Support

6.1 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

6.2 Trademarks

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6.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

6.4 Glossary

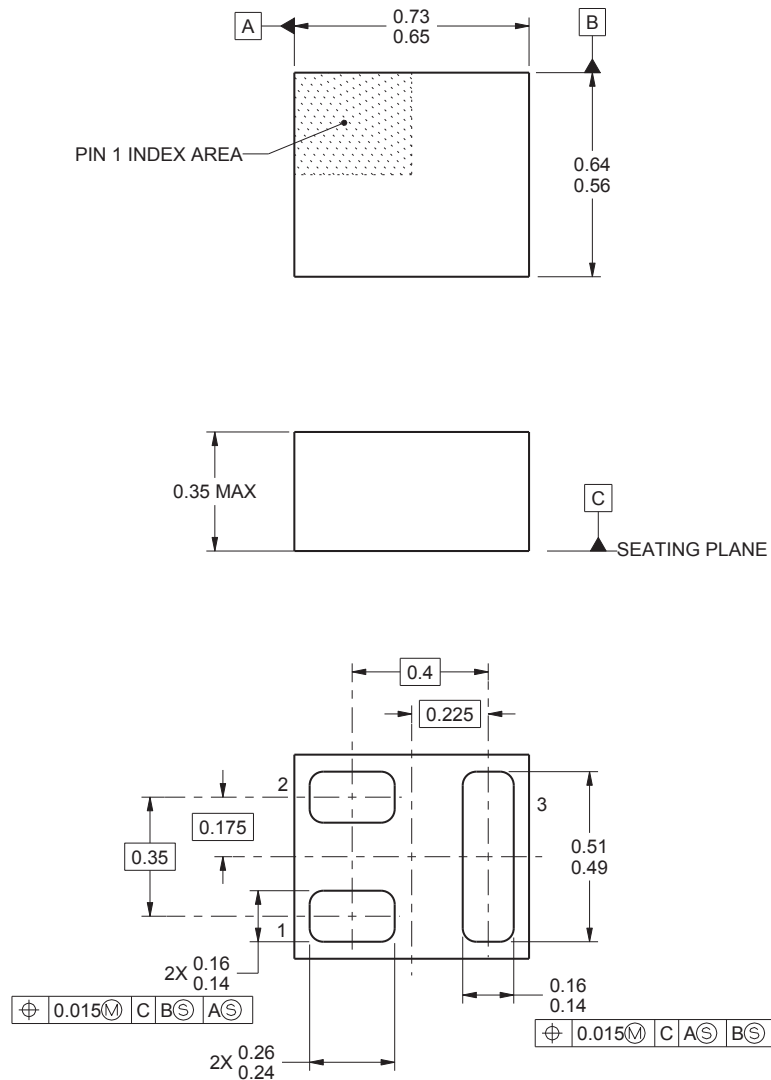
[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

7 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

7.1 Mechanical Dimensions

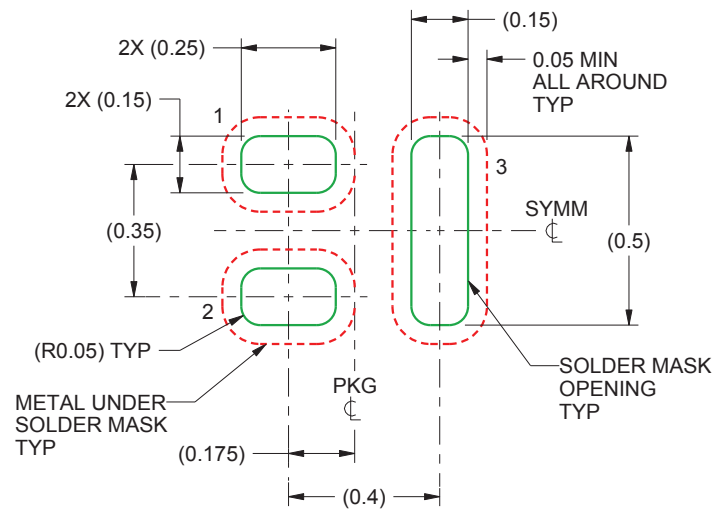


- (1) All linear dimensions are in millimeters (dimensions and tolerancing per AME T14.5M-1994).
- (2) This drawing is subject to change without notice.
- (3) This package is a PB-free solder land design.

Pin Configuration

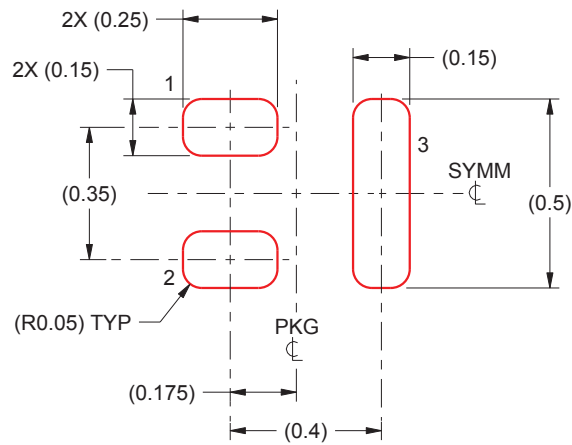
| Position | Designation |
|----------|-------------|
| Pin 1 | Gate |
| Pin 2 | Source |
| Pin 3 | Drain |

7.2 Recommended Minimum PCB Layout



(1) All dimensions are in millimeters.

7.3 Recommended Stencil Pattern



(1) All dimensions are in millimeters.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| CSD15380F3 | ACTIVE | PICOSTAR | YJM | 3 | 3000 | Green (RoHS & no Sb/Br) | Call TI | Level-1-260C-UNLIM | -55 to 150 | 6 | Samples |
| CSD15380F3T | ACTIVE | PICOSTAR | YJM | 3 | 250 | Green (RoHS & no Sb/Br) | Call TI | Level-1-260C-UNLIM | -55 to 150 | 6 | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CSD15380F3 | PICOST AR | YJM | 3 | 3000 | 178.0 | 8.4 | 0.7 | 0.79 | 0.44 | 4.0 | 8.0 | Q2 |
| CSD15380F3 | PICOST AR | YJM | 3 | 3000 | 180.0 | 8.4 | 0.7 | 0.79 | 0.44 | 4.0 | 8.0 | Q2 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CSD15380F3 | PICOSTAR | YJM | 3 | 3000 | 220.0 | 220.0 | 35.0 |
| CSD15380F3 | PICOSTAR | YJM | 3 | 3000 | 182.0 | 182.0 | 20.0 |

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